

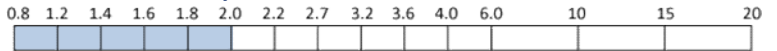
CP Serie Thermal Pad



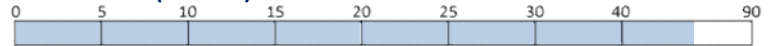
Features

- Low thermal contact resistance
- Electrically isolating
- Decrease the weight of the product
- Easy to assemble
- Thermal conduction and buffer effect

Thermal Conductivity : 2 W / mK



Hardness : 65 (Shore A)



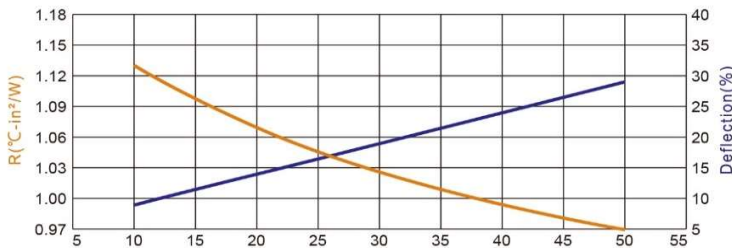
Standard Sizes

1. CP22 TO -220:11.4 x 16 x 5.8
2. CP23 TO -220:11.4 x 21.5 x 5.8
3. CP33 TO -220:17.5 x 28.5 x 5.8

Applications

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in ² /W)	Deflection (%)
10	1.13	9
30	1.07	14
50	0.97	29

Properties

Properties	CP22/CP23/CP33	Unit	Tolerance	Test Method
Thermal Conductivity	2.0	W / mK	±10%	ASTM D5470
Thickness	0.3 / 0.45	mm	-	ASTM D374
Color	Gray	-	-	Visual
Material	Silicone	-	-	-
Working Temperature	-45 ~ +180	°C	-	-
Density	2.6	g / cm ³	-	ASTM D792
Dielectric Breakdown Voltage	4.1 / 6.1	KV	±0.4/±0.6	ASTM D149
Dielectric Breakdown Voltage	6.1 / 8.1	KV	±0.6/±0.8	ASTM D149
Dielectric Constant	5.8	1000 Hz	-	ASTM D150
Thermal Impedance @10psi	1.13	°C-in ² / W	-	ASTM D5470
Thermal Impedance @20psi	1.07	°C-in ² / W	-	ASTM D5470
Thermal Impedance @50psi	0.97	°C-in ² / W	-	ASTM D5470
Hardness	65	Shore A	±7	ASTM D2240

高柏科技 T-Global Technology Co., Ltd

Provide professional thermal engineering solutions and full range of products.

桃園市桃園區大仁路50巷33號 No. 33, Ln. 50, Daren Rd., Taoyuan Dist., Taoyuan City 330, Taiwan

T: +886-3-3618899 M: service@tglobal.com.tw W: www.tglobalcorp.com

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